16 M EDO DRAM (1-Mword × 16-bit) 1 k Refresh

HITACHI

ADE-203-636D (Z) Rev. 4.0 Nov. 1997

Description

The Hitachi HM5118165 is a CMOS dynamic RAM organized as 1,048,576-word \times 16-bit. It employs the most advanced 0.5 μ m CMOS technology for high performance and low power. The HM5118165 offers Extended Data Out (EDO) Page Mode as a high speed access mode. It is packaged in 42-pin plastic SOJ and 50-pin plastic TSOP II.

Features

- Single 5 V (±10%)
- Access time: 50 ns/60 ns/70 ns (max)
- Power dissipation
 - Active mode : 1045 mW/935 mW/825 mW (max)
 - Standby mode: 11 mW (max)
 - : 0.83 mW (max) (L-version)
- EDO page mode capability
- Refresh cycles
 - 1024 refresh cycles: 16 ms

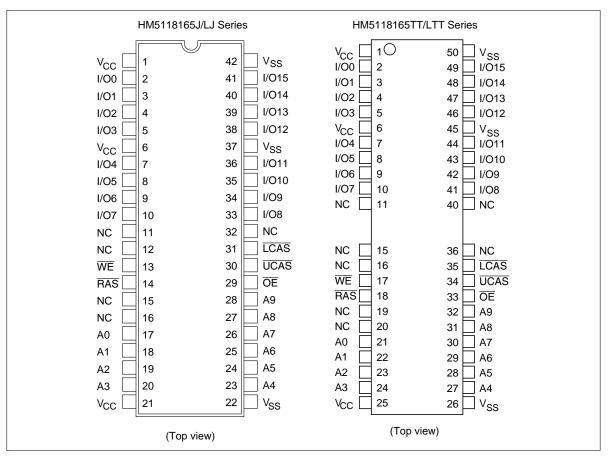
: 128 ms (L-version)

- 4 variations of refresh
 - RAS-only refresh
 - CAS-before-RAS refresh
 - Hidden refresh
 - Self refresh (L-version)
- 2CAS-byte control
- Battery backup operation (L-version)

Ordering Information

Type No.	Access time	Package
HM5118165J-5	50 ns	400-mil 42-pin plastic SOJ (CP-42D)
HM5118165J-6	60 ns	
HM5118165J-7	70 ns	
HM5118165LJ-5	50 ns	
HM5118165LJ-6	60 ns	
HM5118165LJ-7	70 ns	
HM5118165TT-5	50 ns	400-mil 50-pin plastic TSOP II (TTP-50/44DC)
HM5118165TT-6	60 ns	
HM5118165TT-7	70 ns	
HM5118165LTT-5	50 ns	
HM5118165LTT-6	60 ns	
HM5118165LTT-7	70 ns	

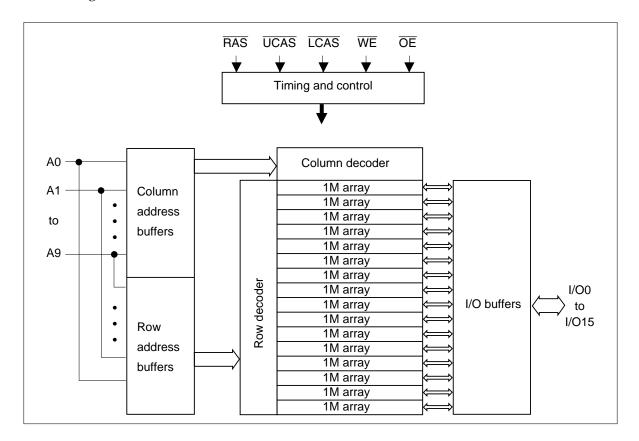
Pin Arrangement



Pin Description

Pin name	Function
A0 to A9	Address input — Row/Refresh address A0 to A9 — Column address A0 to A9
I/O0 to I/O15	Data input/Data output
RAS	Row address strobe
UCAS, LCAS	Column address strobe
WE	Read/Write enable
ŌĒ	Output enable
V _{cc}	Power supply
V _{ss}	Ground
NC	No connection

Block Diagram



Truth Table

RAS	LCAS	UCAS	WE	OE	Output		Operation
Н	D	D	D	D	Open		Standby
L	L	Н	Н	L	Valid	Lower byte	Read cycle
L	Н	L	Н	L	Valid	Upper byte	-
L	L	L	Н	L	Valid	Word	_
L	L	Н	L*2	D	Open	Lower byte	Early write cycle
L	Н	L	L*2	D	Open	Upper byte	-
L	L	L	L*2	D	Open	Word	-
L	L	Н	L*2	Н	Undefined	Lower byte	Delayed write cycle
L	Н	L	L*2	Н	Undefined	Upper byte	-
L	L	L	L*2	Н	Undefined	Word	-
L	L	Н	H to L	L to H	Valid	Lower byte	Read-modify-write cycle
L	Н	L	H to L	L to H	Valid	Upper byte	-
L	L	L	H to L	L to H	Valid	Word	-
L	Н	Н	D	D	Open	Word	RAS-only refresh cycle
H to L	Н	L	D	D	Open	Word	CAS-before-RAS refresh cycle or
H to L	L	Н	D	D	Open	Word	Self refresh cycle (L-version)
H to L	L	L	D	D	Open	Word	-
L	L	L	Н	Н	Open		Read cycle (Output disabled)

Notes: 1. H: High (inactive) L: Low (active) D: H or L

- 2. $t_{WCS} \ge 0$ ns Early write cycle
 - t_{WCS} < 0 ns Delayed write cycle
- 3. Mode is determined by the OR function of the UCAS and LCAS. (Mode is set by the earliest of UCAS and LCAS active edge and reset by the latest of UCAS and LCAS inactive edge.)

 However write OPERATION and output High-Z control are done independently by each UCAS, LCAS.

ex. if $\overline{RAS} = H$ to L, $\overline{UCAS} = H$, $\overline{LCAS} = L$, then \overline{CAS} -before- \overline{RAS} refresh cycle is selected.

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Voltage on any pin relative to V _{ss}	V _T	-1.0 to +7.0	V	
Supply voltage relative to V _{SS}	V _{cc}	-1.0 to +7.0	V	
Short circuit output current	lout	50	mA	
Power dissipation	P _T	1.0	W	
Operating temperature	Topr	0 to +70	°C	
Storage temperature	Tstg	-55 to +125	°C	

Recommended DC Operating Conditions ($Ta = 0 \text{ to } +70^{\circ}C$)

Parameter	Symbol	Min	Тур	Max	Unit	Notes
Supply voltage	V _{CC}	4.5	5.0	5.5	V	1, 2
Input high voltage	V _{IH}	2.4	_	6.5	V	1
Input low voltage	V _{IL}	-1.0	_	0.8	V	1

Notes: 1. All voltage referred to V_{ss}

2. The supply voltage with all V_{cc} pins must be on the same level. The supply voltage with all V_{ss} pins must be on the same level.

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V \pm 10%, V_{SS} = 0 V)

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		-5		-6		-7		•			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test conditions		
Operating current*1, *2	I _{CC1}	_	200	_	170	_	150	mA	t _{RC} = min		
Standby current	I _{CC2}	_	2	_	2	_	2	mA	TTL interface RAS, UCAS, LCAS = V _{IH} Dout = High-Z		
		_	1		1	_	1	mA	CMOS interface RAS, UCAS, $\overline{\text{LCAS}} \ge V_{\text{cc}} - 0.2 \text{ V}$ Dout = High-Z		
Standby current (L-version)	I _{CC2}	_	150	_	150	_	150	μΑ	CMOS interface RAS, UCAS, $\overline{\text{LCAS}} \ge V_{\text{cc}} - 0.2 \text{ V}$ Dout = High-Z		

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V \pm 10%, V_{SS} = 0 V) (cont.)

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		-5		-6		-7		-	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test conditions
RAS-only refresh current*2	I _{CC3}	_	200	_	170	_	150	mA	t _{RC} = min
Standby current*1	I _{CC5}	_	5	_	5	_	5	mA	$\overline{RAS} = V_{IH},$ $\overline{UCAS}, \overline{LCAS} = V_{IL}$ $Dout = enable$
CAS-before-RAS refresh current	I _{CC6}		190	_	170		150	mA	t _{RC} = min
EDO page mode current*1, *3	I _{CC7}	_	185	_	165	_	145	mA	t _{HPC} = min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I _{CC10}		500		500	_	500	μА	CMOS interface Dout = High-Z CBR refresh: t_{RC} = 125 μ S $t_{RAS} \le 0.3 \ \mu$ S
Self refresh mode current (L-version)	I _{CC11}	_	300		300		300	μА	CMOS interface RAS, UCAS, LCAS ≤ 0.2 V Dout = High-Z
Input leakage current	ILI	-10	10	-10	10	-10	10	μΑ	0 V ≤ Vin ≤ 7 V
Output leakage current	I _{LO}	-10	10	-10	10	-10	10	μΑ	0 V ≤ Vout ≤ 7 V Dout = disable
Output high voltage	V_{OH}	2.4	V_{cc}	2.4	V_{cc}	2.4	V_{cc}	V	High lout = −2 mA
Output low voltage	V _{OL}	0	0.4	0	0.4	0	0.4	V	Low lout = 2 mA

Notes: 1. I_{cc} depends on output load condition when the device is selected. I_{cc} max is specified at the output open condition.

- 2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.
- 3. Address can be changed once or less while \overline{UCAS} and $\overline{LCAS} = V_{IH}$.
- 4. $V_{IH} \ge V_{CC} 0.2 \text{ V}, \text{ 0 V} \le V_{IL} \le 0.2 \text{ V}.$

Capacitance (Ta = 25°C, V_{CC} = 5 V ± 10%)

Parameter	Symbol	Тур	Max	Unit	Notes
Input capacitance (Address)	C _{I1}	_	5	pF	1
Input capacitance (Clocks)	C _{I2}		7	pF	1
Output capacitance (Data-in, Data-out)	C _{I/O}	_	7	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. \overline{RAS} , \overline{UCAS} and $\overline{LCAS} = V_{IH}$ to disable Dout.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V \pm 10%, V_{SS} = 0 V)* 1 , * 2 , * 18 , * 19 , * 20

Test Conditions

Input rise and fall time: 2 nsInput levels: 0 V, 3.0 V

Input timing reference levels: 0.8 V, 2.4 V
Output timing reference levels: 0.8 V, 2.0 V

• Output load: $1 \text{ TTL gate} + C_L (100 \text{ pF}) (Including scope and jig)$

Read, Write, Read-Modify-Write and Refresh Cycles (Common parameters)

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		-5		-6		-7		•	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t _{RC}	84	_	104	_	124	_	ns	
RAS precharge time	t _{RP}	30	_	40	_	50	_	ns	
CAS precharge time	t _{CP}	7		10	_	13	_	ns	
RAS pulse width	t _{RAS}	50	10000	60	10000	70	10000	ns	
CAS pulse width	t _{CAS}	7	10000	10	10000	13	10000	ns	
Row address setup time	t _{ASR}	0		0	_	0	_	ns	
Row address hold time	t _{RAH}	7		10	_	10	_	ns	
Column address setup time	t _{ASC}	0	_	0	_	0	_	ns	21
Column address hold time	t _{CAH}	7		10	_	13	_	ns	21
RAS to CAS delay time	t _{RCD}	11	37	14	45	14	52	ns	3
RAS to column address delay time	t _{RAD}	9	25	12	30	12	35	ns	4
RAS hold time	t _{RSH}	10		13	_	13	_	ns	
CAS hold time	t _{CSH}	35	_	40	_	45	_	ns	23
CAS to RAS precharge time	t _{CRP}	5	_	5	_	5	_	ns	22
OE to Din delay time	t _{OED}	13		15	_	18	_	ns	5
OE delay time from Din	t _{DZO}	0	_	0	_	0	_	ns	6
CAS delay time from Din	t _{DZC}	0	_	0	_	0	_	ns	6
Transition time (rise and fall)	t _T	2	50	2	50	2	50	ns	7

Read Cycle

HM5118165

		-5		-6		-7		_		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes	
Access time from RAS	t _{RAC}	_	50	_	60	_	70	ns	8, 9	
Access time from CAS	t _{CAC}		13	_	15	_	18	ns	9, 10, 17	
Access time from address	t _{AA}	_	25	_	30	_	35	ns	9, 11, 17	
Access time from OE	t _{OEA}	_	13	_	15	_	18	ns	9	
Read command setup time	t _{RCS}	0	_	0	_	0	_	ns	21	
Read command hold time to CAS	t _{RCH}	0	_	0	_	0	_	ns	12, 22	
Read command hold time from RAS	t _{RCHR}	50	_	60	_	70		ns		
Read command hold time to RAS	t _{RRH}	0	_	0	_	0		ns	12	
Column address to RAS lead time	t _{RAL}	25	_	30	_	35	_	ns		
Column address to CAS lead time	t _{CAL}	15	_	18	_	23	_	ns		
CAS to output in low-Z	t _{CLZ}	0	_	0	_	0		ns		
Output data hold time	t _{oh}	3	_	3	_	3	_	ns	27	
Output data hold time from OE	t _{oho}	3	_	3	_	3	_	ns		
Output buffer turn-off time	t _{OFF}	_	13	_	15	_	15	ns	13, 27	
Output buffer turn-off to OE	t _{OEZ}	_	13	_	15	_	15	ns	13	
CAS to Din delay time	t _{CDD}	13	_	15	_	18	_	ns	5	
Output data hold time from RAS	t _{OHR}	3	_	3	_	3	_	ns	27	
Output buffer turn-off to RAS	t _{OFR}	_	13	_	15	_	15	ns	27	
Output buffer turn-off to WE	t _{wez}	_	13	_	15	_	15	ns		
WE to Din delay time	t _{WED}	13	_	15	_	18	_	ns		
RAS to Din delay time	t _{RDD}	13		15	_	18		ns		
RAS next CAS delay time	t _{RNCD}	50		60		70	_	ns		

Write Cycle

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		-5		-6		-7		_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write command setup time	t _{wcs}	0	_	0	_	0	_	ns	14, 21
Write command hold time	t _{wch}	7	_	10	_	13	_	ns	21
Write command pulse width	t _{wP}	7	_	10		10	_	ns	
Write command to RAS lead time	t _{RWL}	7	_	10		13		ns	
Write command to CAS lead time	t _{cwL}	7	_	10		13	_	ns	23
Data-in setup time	t _{DS}	0	_	0		0	_	ns	15, 23
Data-in hold time	t _{DH}	7	_	10	_	13	_	ns	15, 23

Read-Modify-Write Cycle

		-5		-6		-7		_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read-modify-write cycle time	t _{RWC}	111	_	135	_	161	_	ns	
RAS to WE delay time	t _{RWD}	67	_	79	_	92	_	ns	14
CAS to WE delay time	t _{CWD}	30	_	34	_	40	_	ns	14
Column address to WE delay time	t _{AWD}	42	_	49	_	57	_	ns	14
OE hold time from WE	t _{OEH}	13	_	15	_	18	_	ns	

Refresh Cycle

HM5118165

		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
CAS setup time (CBR refresh cycle)	t _{CSR}	5	_	5	_	5	_	ns	21
CAS hold time (CBR refresh cycle)	t _{CHR}	7	_	10	_	10	_	ns	22
RAS precharge to CAS hold time	t _{RPC}	5	_	5		5	_	ns	21

EDO Page Mode Cycle

HM5118165

		-5		-6 -7		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
EDO page mode cycle time	t _{HPC}	20	_	25	_	30	_	ns	25
EDO page mode RAS pulse width	t _{RASP}	_	100000	_	100000	_	100000	ns	16
Access time from CAS precharge	t _{CPA}	_	28	_	35	_	40	ns	9, 17, 22
RAS hold time from CAS precharge	t _{CPRH}	28		35	_	40	_	ns	
Output data hold time from CAS low	t _{DOH}	3	_	3	_	3	_	ns	9
CAS hold time referred OE	t _{COL}	7	_	10		13	_	ns	
CAS to OE setup time	t _{COP}	5		5	_	5	_	ns	
Read command hold time from CAS precharge	t _{RCHC}	28	_	35	_	40	_	ns	

EDO Page Mode Read-Modify-Write Cycle

HM5118165

		-5		-6		-7		_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
EDO page mode read-modify-write cycle time	t _{HPRWC}	57	_	68	_	79	_	ns	
WE delay time from CAS precharge	t _{CPW}	45	_	54	_	62	_	ns	14, 22

Refresh

Parameter	Symbol	Max	Unit	Note	
Refresh period	t _{REF}	16	ms	1024 cycles	
Refresh period (L-version)	t _{REF}	128	ms	1024 cycles	

Self Refresh Mode (L-version)

HM5118165L

		-5		-6		-7		_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
RAS pulse width (self refresh)	t _{RASS}	100	_	100	_	100	_	μs	28, 29, 30, 31
RAS precharge time (self refresh)	t _{RPS}	90	_	110	_	130	_	ns	
CAS hold time (self refresh)	t _{CHS}	-50	_	-50	_	-50	_	ns	-

Notes: 1. AC measurements assume $t_{\tau} = 2$ ns.

- 2. An initial pause of 200 µs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing RAS-only refresh or CAS-before-RAS refresh).
- 3. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if $t_{RCD} \ge t_{RAD}$ (max) + t_{AA} (max) t_{CAC} (max), then access time is controlled exclusively by t_{CAC} .
- 4. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.
- 5. Either t_{OED} or t_{CDD} must be satisfied.
- 6. Either $t_{\rm DZO}$ or $t_{\rm DZC}$ must be satisfied.
- 7. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
- 8. Assumes that $t_{RCD} \le t_{RCD}$ (max) and $t_{RAD} \le t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
- 9. Measured with a load circuit equivalent to 1 TTL loads and 100 pF.
- 10. Assumes that $t_{RCD} \ge t_{RCD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\ge t_{RAD} + t_{AA}$ (max).
- 11. Assumes that $t_{RAD} \ge t_{RAD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\le t_{RAD} + t_{AA}$ (max).
- 12. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
- 13. t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
- 14. t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \ge t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if t_{RWD} $\ge t_{RWD}$ (min), $t_{CWD} \ge t_{CWD}$ (min), and $t_{AWD} \ge t_{AWD}$ (min), or $t_{CWD} \ge t_{CWD}$ (min), $t_{AWD} \ge t_{AWD}$ (min) and $t_{CPW} \ge t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 15. These parameters are referred to UCAS and LCAS leading edge in early write cycles and to WE leading edge in delayed write or read-modify-write cycles.
- 16. t_{RASP} defines RAS pulse width in EDO page mode cycles.
- 17. Access time is determined by the longest among t_{AA} , t_{CAC} and t_{CPA} .
- 18. In delayed write or read-modify-write cycles, \overline{OE} must disable output buffer prior to applying data to the device.
- 19. When both UCAS and LCAS go low at the same time, all 16-bit data are written into the device.

 UCAS and LCAS cannot be staggered within the same write/read cycles.

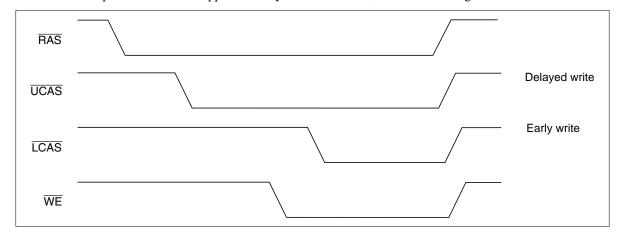
- 20 All the V_{cc} and V_{ss} pins shall be supplied with the same voltages.
- 21. t_{ASC} , t_{CAH} , t_{RCS} , t_{WCS} , t_{WCH} , t_{CSR} and t_{RPC} are determined by the earlier falling edge of \overline{UCAS} or \overline{LCAS} .
- 22. t_{CRP} , t_{CHR} , t_{RCH} , t_{CPA} and t_{CPW} are determined by the later rising edge of \overline{UCAS} or \overline{LCAS} .
- 23. t_{CWL} , t_{DH} , t_{DS} and t_{CSH} should be satisfied by both $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.
- 24. t_{CP} is determined by the time that both UCAS and LCAS are high.
- 25. t_{HPC} (min) can be achieved during a series of EDO page mode write cycles or EDO page mode read cycles. If both write and read operation are mixed in a EDO page mode \overline{RAS} cycle (EDO page mode mix cycle (1), (2)), minimum value of \overline{CAS} cycle ($t_{CAS} + t_{CP} + 2 t_{T}$) becomes greater than the specified t_{HPC} (min) value. The value of \overline{CAS} cycle time of mixed EDO page mode is shown in EDO page mode mix cycle (1) and (2).
- 26. When output buffers are enabled once, sustain the low impedance state until valid data is obtained. When output buffer is turned on and off within a very short time, generally it causes large V_{CC}/V_{SS} line noise, which causes to degrade V_{IH} min/V_{IL} max level.
- 27. Data output turns off and becomes high impedance from later rising edge of \overline{RAS} and \overline{CAS} . Hold time and turn off time are specified by the timing specifications of later rising edge of \overline{RAS} and \overline{CAS} between t_{OHR} and t_{OHR} , and between t_{OFR} and t_{OFF} .
- 28. Please do not use t_{RASS} timing, 10 $\mu s \le t_{RASS} \le 100 \ \mu s$. During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{RASS} \ge 100 \ \mu s$, then \overline{RAS} precharge time should use t_{RPS} instead of t_{RPS} .
- 29. If you use distributed CBR refresh mode with 15.6 μs interval in normal read/write cycle, CBR refresh should be executed within 15.6 μs immediately after exiting from and before entering into self refresh mode.
- 30. If you use RAS only refresh or CBR burst refresh mode in normal read/write cycle, 1024 cycles of distributed CBR refresh with 15.6 μs interval should be executed within 16 ms immediately after exiting from and before entering into the self refresh mode.
- 31. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self fresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.
- 32. XXX: H or L (H: V_{IH} (min) $\leq V_{IN} \leq V_{IH}$ (max), L: V_{IL} (min) $\leq V_{IN} \leq V_{IL}$ (max)) //////: Invalid Dout

When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL} .

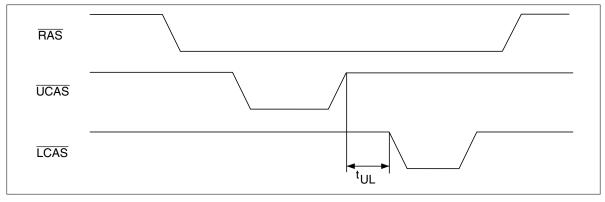
Notes concerning 2CAS control

Please do not separate the $\overline{UCAS}/\overline{LCAS}$ operation timing intentionally. However skew between $\overline{UCAS}/\overline{LCAS}$ are allowed under the following conditions.

- 1. Each of the UCAS/LCAS should satisfy the timing specifications individually.
- 2. Different operation mode for upper/lower byte is not allowed; such as following.



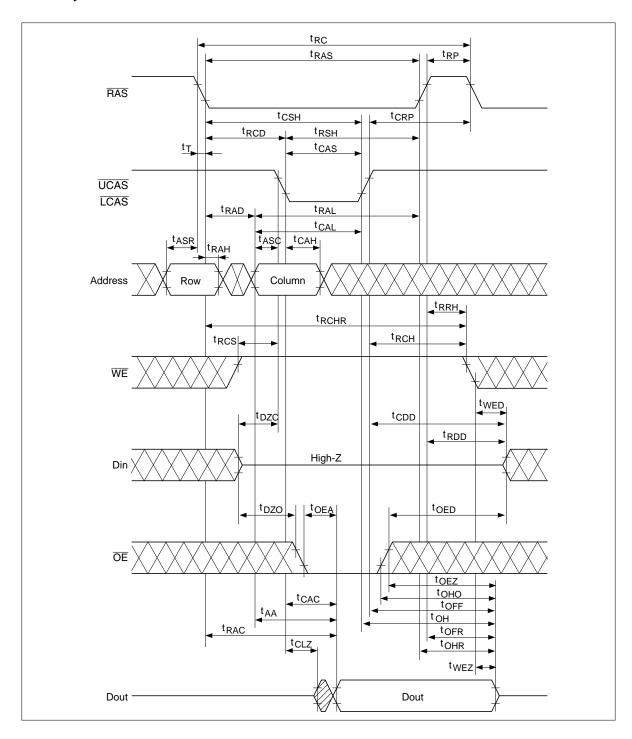
3. Closely separated upper/lower byte control is not allowed. However when the condition $(t_{CP} \le t_{UL})$ is satisfied, EDO page mode can be performed.



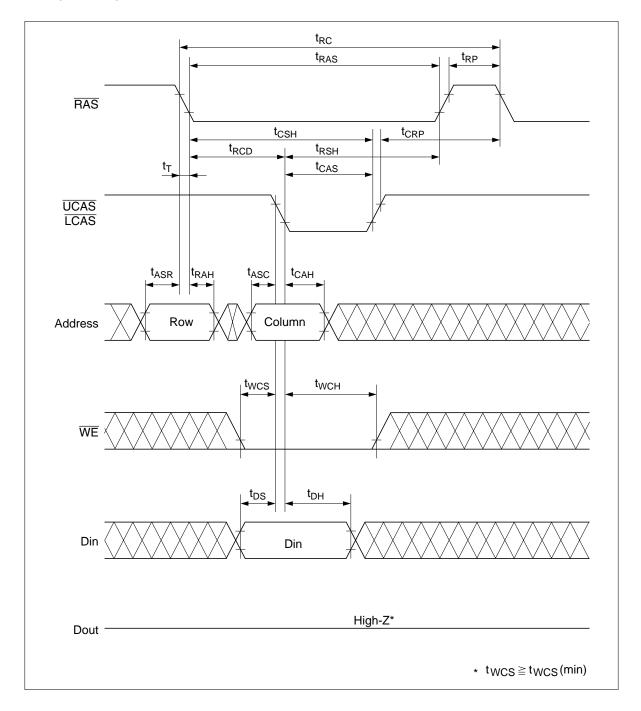
4. Byte control operation by remaining \overline{UCAS} or \overline{LCAS} high is guaranteed.

Timing Waveforms*32

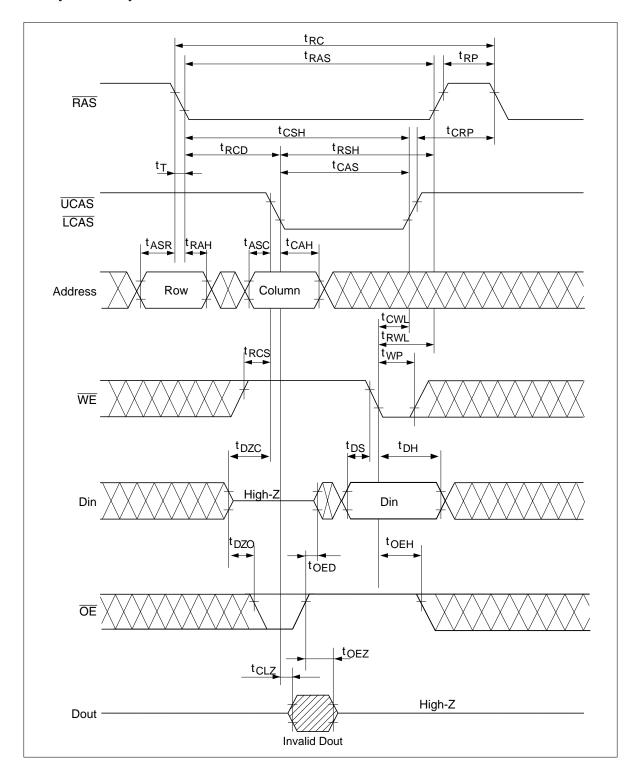
Read Cycle



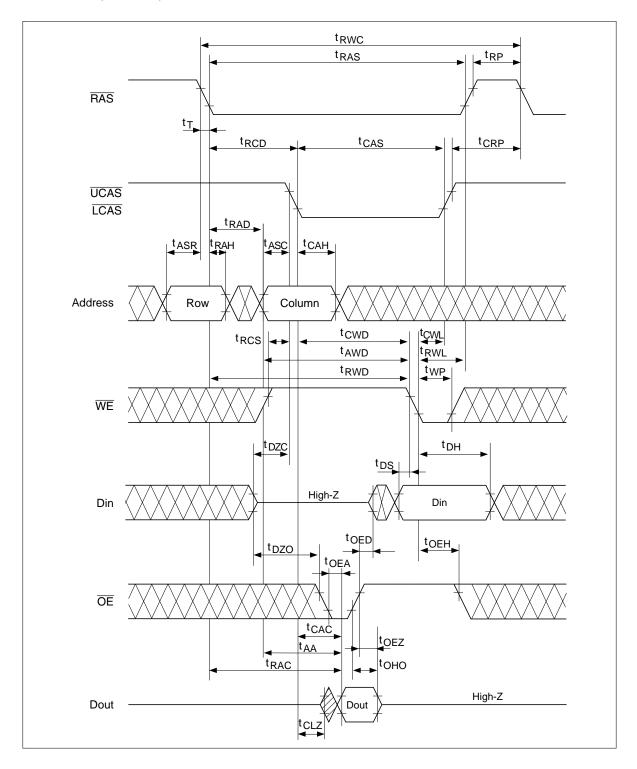
Early Write Cycle



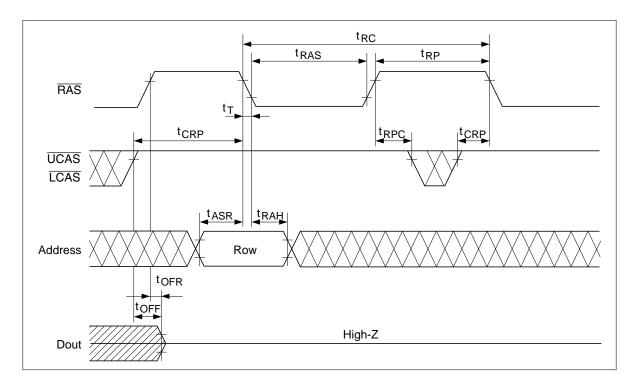
Delayed Write Cycle*18



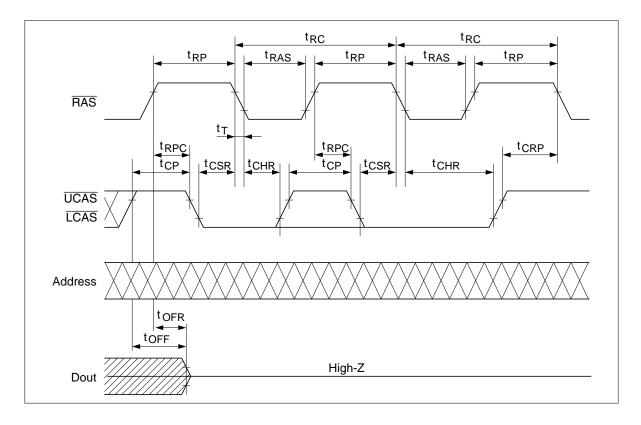
Read-Modify-Write Cycle*18



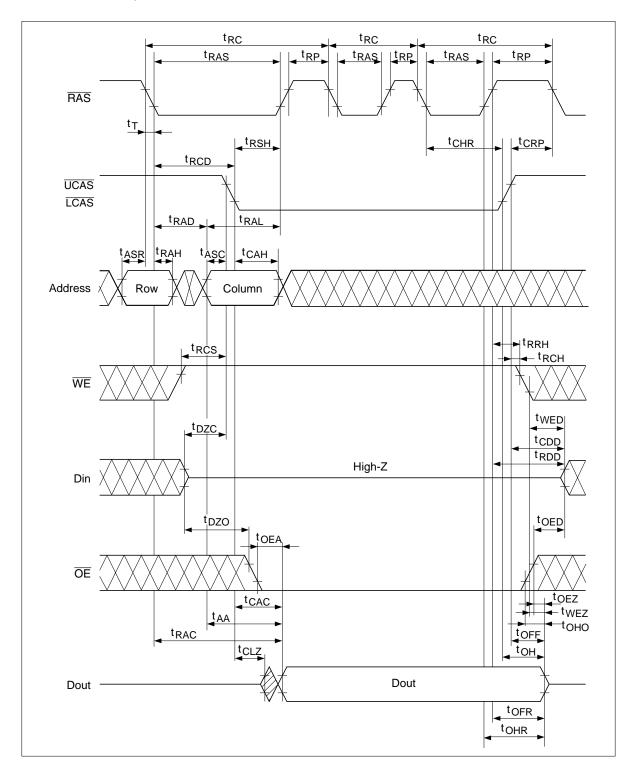
\overline{RAS} -Only Refresh Cycle



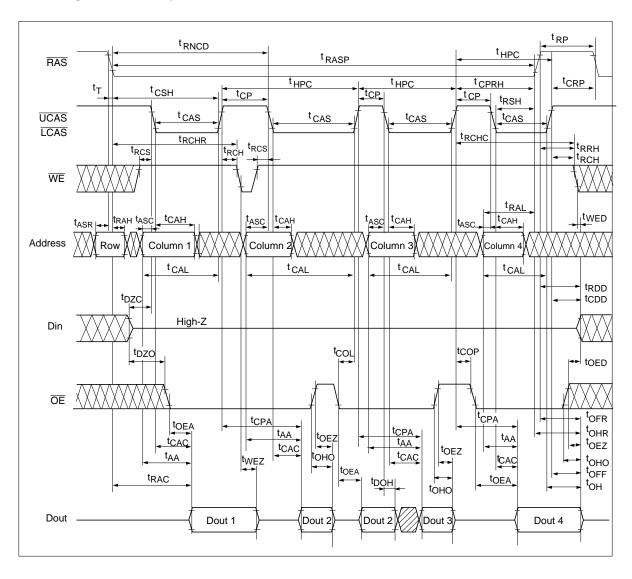
$\overline{\text{CAS}}\text{-Before-}\overline{\text{RAS}}$ Refresh Cycle



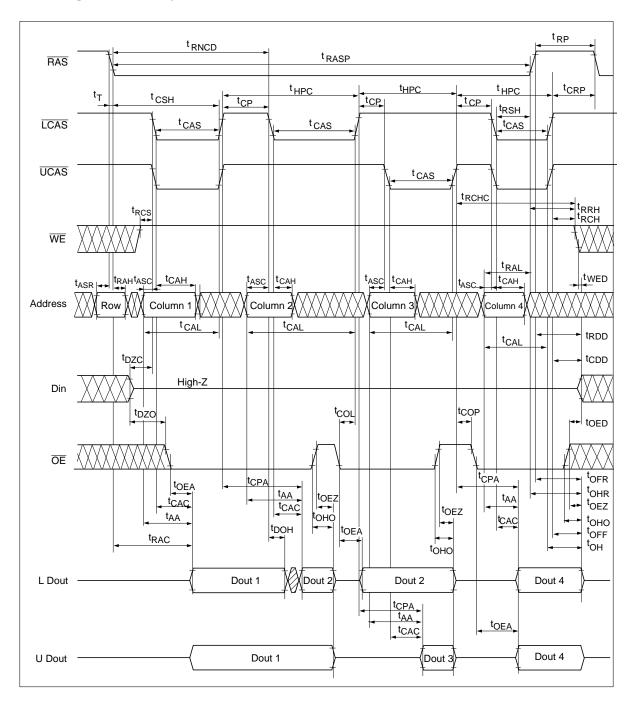
Hidden Refresh Cycle



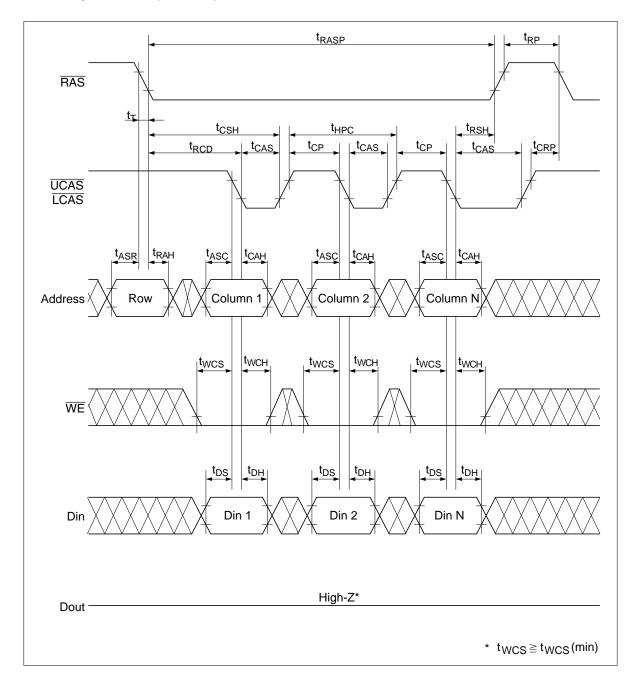
EDO Page Mode Read Cycle



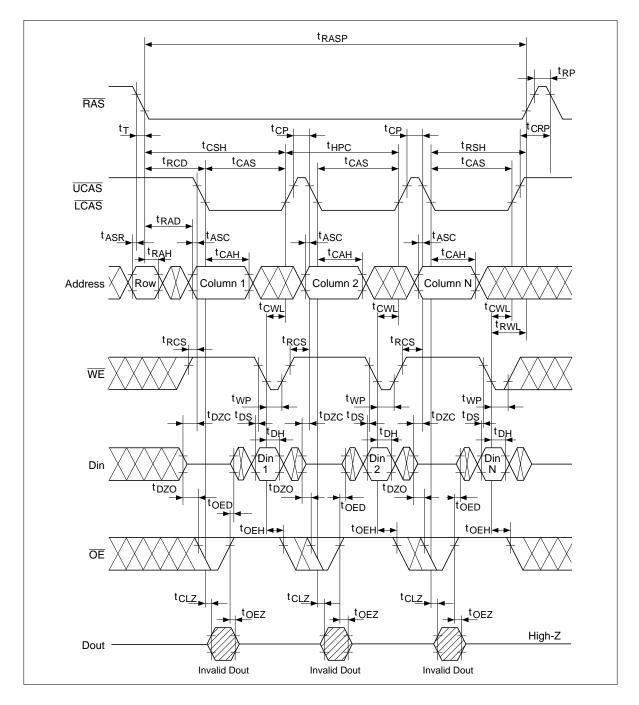
EDO Page Mode Read Cycle (2CAS)



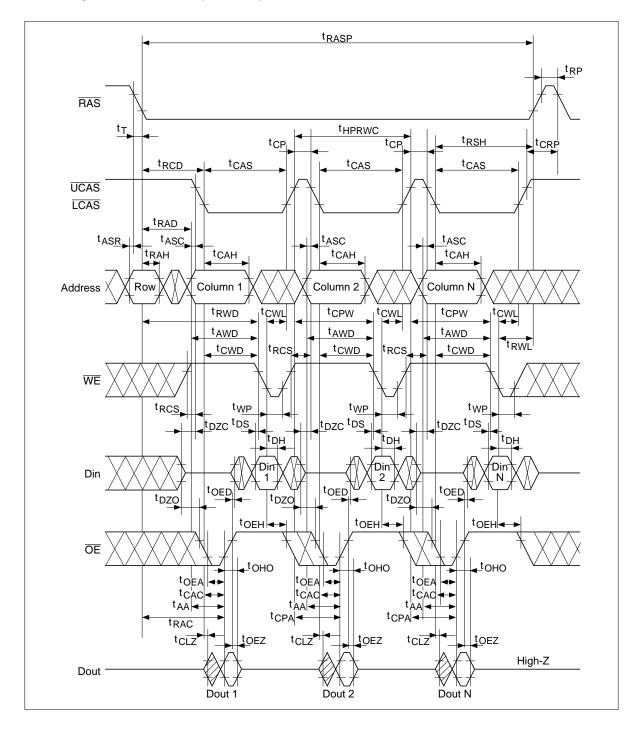
EDO Page Mode Early Write Cycle



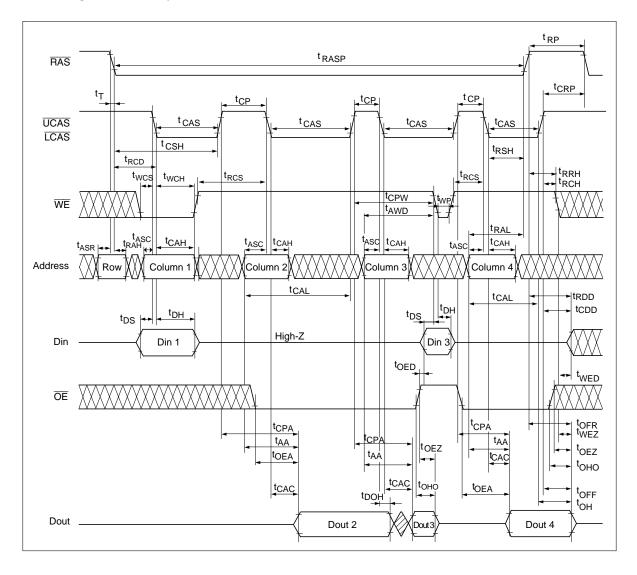
EDO Page Mode Delayed Write Cycle* 18



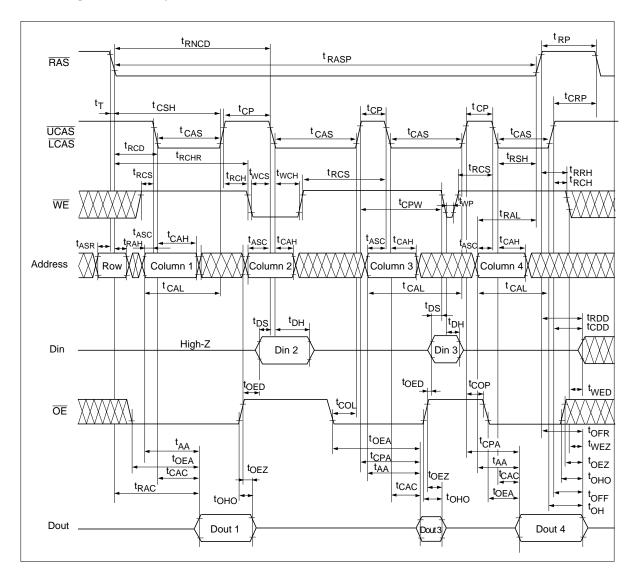
EDO Page Mode Read-Modify-Write Cycle*18



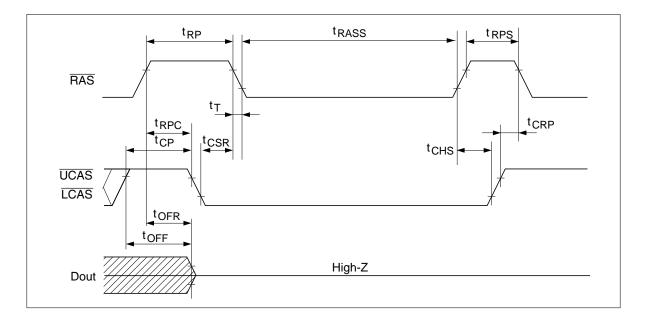
EDO Page Mode Mix Cycle (1)



EDO Page Mode Mix Cycle (2)

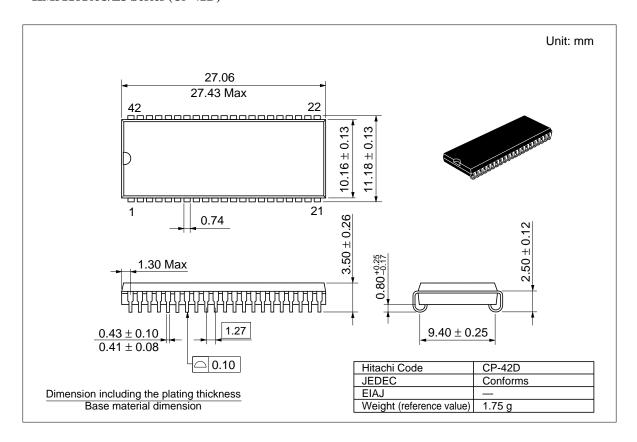


Self Refresh Cycle (L-version)*28, 29, 30, 31

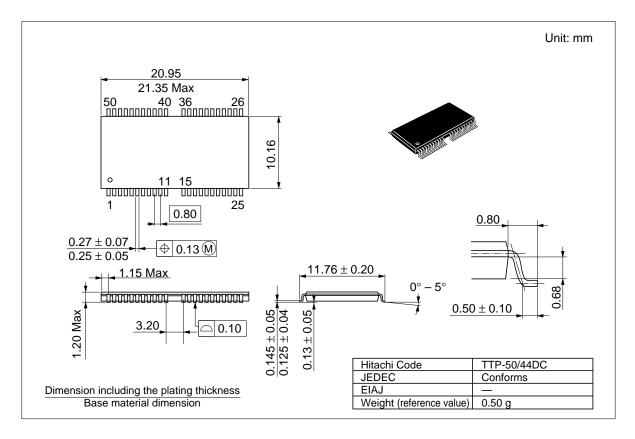


Package Dimensions

HM5118165J/LJ Series (CP-42D)



HM5118165TT/LTT Series (TTP-50/44DC)



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IITACHI

Hitachi, Ltd.

Semiconductor & IC Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

For further information write to:

Hitachi Semiconductor (America) Inc. 2000 Sierra Point Parkway Brisbane, CA. 94005-1897 USA Tel: 800-285-1601 Fax:303-297-0447

Hitachi Europe GmbH Continental Europe Dornacher Straße 3 D-85622 Feldkirchen München Tel: 089-9 91 80-0 Fax: 089-9 29 30-00

Hitachi Europe Ltd. Electronic Components Div. Northern Europe Headquarters Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA United Kingdom Tel: 01628-585000 Fax: 01628-585160

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia (Hong Kong) Ltd. Unit 706, North Tower, World Finance Centre. Harbour City, Canton Road Tsim Sha Tsui, Kowloon Hong Kong Tel: 27359218

Fax: 27306071

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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Sep. 30, 1996	Initial issue	Y. Kasama	M. Mishima
2.0	Nov. 26, 1996	Addition of HM5118165-5 Series	Y. Kasama	M. Mishima
		Power dissipation (active)		
		1018/907 mW(max) to 1045/935/825 mW (max)		
		DC Characteristics		
		I _{CC7} max: 185/165 mA to 185/165/145 mA		
		AC Characteristics		
		t_{RCD} min: 20/20 ns to 11/14/14 ns t_{RAD} min: 15/15 ns to 9/12/12 ns t_{RSH} min: 15/18 ns to 10/13/13 ns t_{RRH} min: 0/0 ns to 5/5/5 ns t_{RWC} min: 136/161 ns to 111/135/161 ns t_{RPC} min: 0/0 ns to 5/5/5 ns		
		Timing Waveforms		
		Addition of $t_{\mbox{\scriptsize RNCD}}$ timing to EDO page mode mix cycle (2)		
3.0	Feb. 24, 1997	AC Characteristics t _{RRH} min: 5/5/5 ns to 0/0/0 ns	Y. Kasama	Y. Matsuno
4.0	Nov. 1997	Change of Subtitle		